

PHT

Link To The World

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Carrier Substrate Receiving Cleaning Device

PWG-2501



Device Overview

Advanced chiplet package technology for next-generation semiconductors is being developed, and glass substrates are envisioned for use as carrier substrates in packaging applications. We are able to propose transport and cleaning equipment for these glass carrier substrates.

Introduction Example

This equipment is used for cleaning glass substrates upon reception. It uses only pure water (DIW) without the use of chemical solutions.

<Cleaning Process and Equipment Configuration>

The process follows the sequence outlined below.

(1) Loading Conveyor → (2) Idle → (3) Two-fluid Shower Cleaning → (4) Brush Cleaning → (5) Pure Water Shower Cleaning → (6) Final Rinse Cleaning with Pure Water → (7) Water Removal using Absorption Rollers → (8) Slit Nozzle Drying with Air Knife → (9) Ionizer Blow Drying with LD & ULD (includes Load Port).

Device Specifications

Unit	Specifications
Loading Conveyor Section	□ 600 mm × Plate Thickness 0.7–1.2 mm (1 sheet can be loaded)
Idle Position	Cleaning Loading Standby Section, Equipped with Exhaust Function
Shower (1)	Max 5L/min
Brush Cleaning Section	Pure Water Shower Cleaning + Spiral Brush
Shower (2)	Rinse Cleaning with Pure Water
Shower (3)	Final Rinse Cleaning with Pure Water
Water Removal Roller Section	Water Removal Using Absorbent Rollers
Air Drying Section	Drying Using Air Knives
Ionizer	Ionizer Blow Drying

As an option, it is also possible to load individual sheets using a cassette magazine and robot.